

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Blackshear et al.

Serial No.: 10/056,256

Filed: January 24, 2002

For: VERTICALLY STACKED MEMORY CHIPS IN FBGA PACKAGES

Assistant Commissioner of Patents
Washington, D.C. 20231



Group Art Unit: 2811

Examiner: Unknown

SUBMISSION OF FORMAL DRAWINGS

Sir:

Submitted herewith is one (1) sheet of formal drawings comprising Figs. 1-3 for the above-referenced patent application. Acknowledgment of receipt is respectfully requested. Please substitute these formal drawings for the drawings which were filed with the application.

Respectfully Submitted,

Frederick W. Gibb, III
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Applicant(s): **Blackshear et al.**

Docket No.

FIS9-2000-0273-US1

Serial No.
10/056,256

Filing Date

January 24, 2002

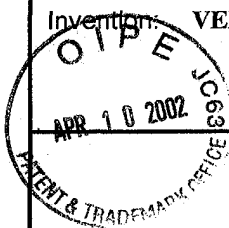
Examiner

Unknown

Group Art Unit

2811

Invention: **VERTICALLY STACKED MEMORY CHIPS IN FBGA PACKAGES**



I hereby certify that this **Submission of Formal Drawings**

(Identify type of correspondence)

is being deposited with the United States Postal Service as first class mail in an envelope addressed to: The

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